

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	1561	219/548	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:41
L7	0	l6 and die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:42
L8	0	6 and die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:42
L9	0	L6 and die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:08
L10	0	219/548 and die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:43
L11	1239	219/209	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:48
L12	1432	219/243	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:48
L13	2651	L11 or L12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:48
L14	18	L13 and die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:00
L15	1	L14 and temperature near2 uniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:54

L16	1	14 and temperature near2 uniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:56
L17	0	14 and temperature near2 non adj uniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:55
L18	5	219/548 and temperature near2 non adj uniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:55
L19	0	14 and temperature near2 uneven	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:57
L20	0	14 and temperature near2 nonuniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 12:57
L21	33	"156"/\$.ccls. and die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:01
L22	28	21 and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:01
L23	0	21 and temperature with various	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:02
L24	4	21 and temperature with differ\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:06
L25	2	14 and temperature with differ\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:09

L26	1674	die same solder\$3 same heat\$3 same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:08
L27	158	26 and temperature with differ\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:09
L28	65	26 and temperature near2 differ\$5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:16
L29	5	28 and no\$uniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:24
L30	2	28 and nozzle	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:16
L31	1	29 and epoxy	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	OR	OFF	2004/10/25 13:25